KOREAN PATENT ABSTRACTS(KR)
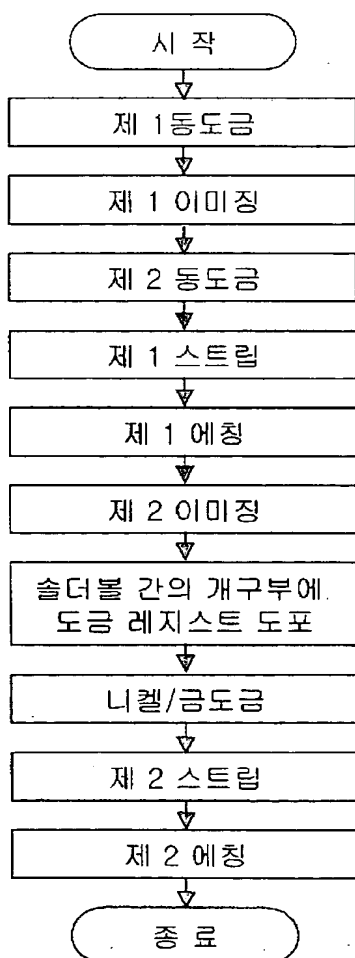
(54) Title of Invention
   METHOD FOR PLATING BUMP PAD OF PRINTED CIRCUIT BOARD FOR FLIP CHIP BGA SEMICONDUCTOR PACKAGE

Representative drawing

시 작

제 1 동도금

제 1 이미징

제 2 동도금

제 1 스트립

제 1 에칭

제 2 이미징

솔더볼 간의 개구부에 도금 레지스트 도포

니켈/금도금

제 2 스트립

제 2 에칭

종 료

(57) Abstract:

PURPOSE: A method is provided to reduce plating defects by permitting the bump pad connected to the solder ball land through a via hole to be electro-plated together with the solder ball land.

CONSTITUTION: A method comprises a first copper plating step of electroless copper plating the solder ball land of a substrate having a via hole; a first imaging step of attaching a dry film on the copper plate land, and exposing only the connection portion between the circuit and the solder ball land by exposing and developing the resultant structure; a second copper plating step of forming a lead wire for interconnecting the circuit and the solder ball land; a first strip step of removing the dry film; a first etching step of removing the copper foil from the portion which is not electro-plated; a second imaging step of attaching a solder mask on the solder ball land, and exposing a certain part of the lead wire by exposing and developing the resultant structure; a plating resist

depositing step of depositing a plating resist on the exposed part of the lead wire; an electro nickel/gold plating step of nickel plating the solder ball lands connected to the lead wire and the bump pad connected to the solder ball land, and performing a gold plating process; a second strip step of removing the solder mask and plating resist; and a second etching step of removing the copper foil from the lead wire which is not nickel/gold-plated, by performing an alkali copper etching process.

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